

POWER MODULE PACKAGES

Microsemi's power module packages cover a complete line of industry standard packages as well as new low profile packages featuring lower cost, less stray inductance, and lower parasitic resistance for higher efficiency, higher frequency capability, and lower EMI.

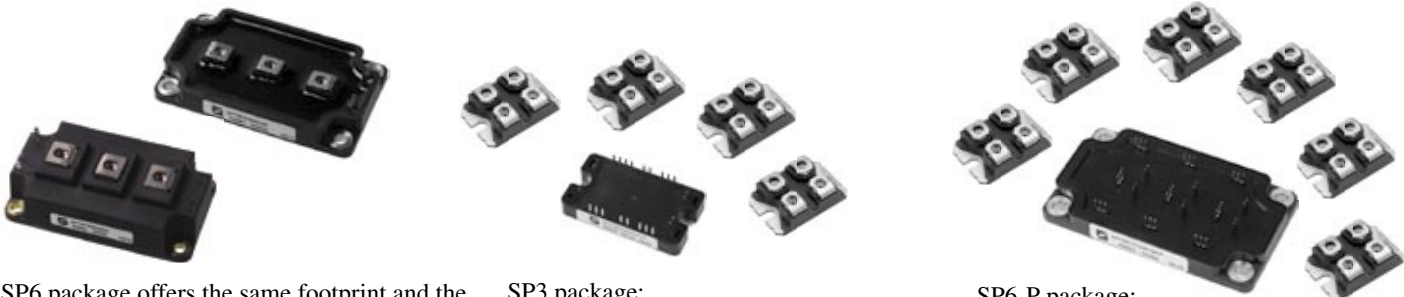
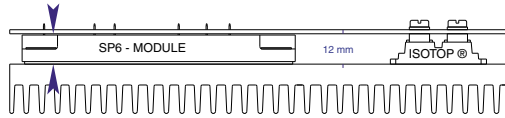
- Lower cost
- Reduced stray inductance
- Reduced parasitic resistance
- Higher efficiency
- Higher frequency capability
- Lower EMI

Improved Low Profile Packages

SP3 (12mm)
SP4 (17mm)
SP6 (17mm)
SP6-P (12mm)



Package Advantages



SP6 package offers the same footprint and the same pinout location as the popular 62mm package but with lower height, leading to:

- reduced stray inductance
- reduced parasitic resistance
- higher efficiency at high frequency

SP3 package:

- Replaces up to 4 SOT-227 parts
- Reduced assembly time and cost
- Height compatible with SOT-227 package
- Copper base plate for high reliability

SP6-P package:

- Replaces up to 6 SOT-227 parts
- Height compatible with SOT-227 package
- Low inductance solder pins
- High current capability

Industry Standard Packages

SOT-227 (Isotop®)



SOT-227

Econo Types

- E2 (Long Pins)
- P2 (Short Pins)
- E3 & P3 (Short Pins)



E2



P2



E3/P3

34mm & 62mm Types

- D1 (34 mm large)
- D3 (62 mm large)
- D4 (62 mm large)



D1



D3



D4